



## News Release



### Unisem Receives 2017 IDP Supplier Excellence Award from Qorvo

**Ipoh, Malaysia, March 2018** – Unisem recently received the 2017 IDP Supplier Excellence Award from its strategic customer Qorvo. The award was presented by Craig Callahan, Qorvo's Director of Quality, to Unisem's Group COO, HL Lee.

Qorvo serves diverse high-growth segments of large global markets, including advanced wireless devices, wired and wireless networks and defense radar and communications. They also leverage their unique competitive strengths to advance 5G networks, cloud computing, the Internet of Things, and other emerging applications that expand the global framework interconnecting people, places and things.

#### About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China and Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia.

For additional information on Unisem, please visit: [www.unisemgroup.com](http://www.unisemgroup.com).

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